



Material Content Data Sheet



Sales Product Name		BSC019N04NS G		Issued		29. August 2013		
MA#		MA001101552						
Package		PG-TDSON-8-1		Weight*		121.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.071	3.34	3.34	33382	33382
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		310	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		93	
	non noble metal	copper	7440-50-8	37.762	30.94	30.98	309626	310029
wire	non noble metal	copper	7440-50-8	0.031	0.03	0.03	254	254
encapsulation	organic material	carbon black	1333-86-4	0.080	0.07		659	
	plastics	epoxy resin	-	5.709	4.68		46807	
	inorganic material	silicondioxide	60676-86-0	34.412	28.22	32.97	282162	329628
leadfinish	non noble metal	tin	7440-31-5	1.452	1.19	1.19	11903	11903
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1357	1357
solder	non noble metal	tin	7440-31-5	0.066	0.05		538	
	noble metal	silver	7440-22-4	0.082	0.07		673	
	non noble metal	lead	7439-92-1	3.135	2.57	2.69	25707	26918
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		93	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	copper	7440-50-8	11.320	9.28	9.29	92818	92939
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		183	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	noble metal	silver	7440-22-4	1.289	1.06		10573	
	non noble metal	copper	7440-50-8	22.292	18.28	19.37	182779	193590
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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